

**SLOVENSKI STANDARD  
SIST EN IEC 60749-30:2020****01-december-2020****Nadomešča:****SIST EN 60749-30:2005****SIST EN 60749-30:2005/A1:2011**

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**Polprevodniški elementi - Mehanske in klimatske preskusne metode - 30. del:  
Predkondicioniranje nehermetičnih elementov za površinsko namestitev pred  
preskušanjem zanesljivosti (IEC 60749-30:2020)**

Semiconductor devices - Mechanical and climatic test methods - Part 30:  
Preconditioning of non-hermetic surface mount devices prior to reliability testing (IEC  
60749-30:2020)

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Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 30:  
Behandlung nicht hermetisch verkappter oberflächenmontierbarer Bauelemente vor  
Zuverlässigkeitsprüfungen (IEC 60749-30:2020)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie  
30: Préconditionnement des composants pour montage en surface non hermétiques  
avant les essais de fiabilité (IEC 60749-30:2020)

**Ta slovenski standard je istoveten z: EN IEC 60749-30:2020**

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**ICS:**

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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**SIST EN IEC 60749-30:2020****en**

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EUROPEAN STANDARD

EN IEC 60749-30

NORME EUROPÉENNE

EUROPÄISCHE NORM

September 2020

ICS 31.080.01

Supersedes EN 60749-30:2005 and all of its  
amendments and corrigenda (if any)

English Version

Semiconductor devices - Mechanical and climatic test methods -  
Part 30: Preconditioning of non-hermetic surface mount devices  
prior to reliability testing  
(IEC 60749-30:2020)

Dispositifs à semiconducteurs - Méthodes d'essais  
mécaniques et climatiques - Partie 30: Préconditionnement  
des composants pour montage en surface non hermétiques  
avant les essais de fiabilité  
(IEC 60749-30:2020)

Halbleiterbauelemente - Mechanische und klimatische  
Prüfverfahren - Teil 30: Behandlung nicht hermetisch  
verkappter oberflächenmontierbarer Bauelemente vor  
Zuverlässigkeitsprüfungen  
(IEC 60749-30:2020)

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European Committee for Electrotechnical Standardization  
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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

**EN IEC 60749-30:2020 (E)****European foreword**

The text of document 47/2633(F)/FDIS, future edition 2 of IEC 60749-30, prepared by IEC/TC 47 “Semiconductor devices” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-30:2020.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2021-06-21 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2023-09-21 document have to be withdrawn

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-4	-	Semiconductor devices - Mechanical and climatic test methods - Part 4: Damp heat, steady-state, highly accelerated stress test (HAST)	EN 60749-4	-
IEC 60749-5	-	Semiconductor devices - Mechanical and climatic test methods - Part 5: Steady-state temperature humidity bias life test	EN 60749-5	-
IEC 60749-11	-	Semiconductor devices - Mechanical and climatic test methods - Part 11: Rapid change of temperature - Two-fluid-bath method	EN 60749-11	-
IEC 60749-20	2020	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	PrEN 60749-20	2020
IEC 60749-24	-	Semiconductor devices - Mechanical and climatic test methods - Part 24: Accelerated moisture resistance - Unbiased HAST	EN 60749-24	-
IEC 60749-25	2003	Semiconductor devices - Mechanical and climatic test methods - Part 25: Temperature cycling	EN 60749-25	2003
IEC 60749-33	-	Semiconductor devices - Mechanical and climatic test methods - Part 33: Accelerated moisture resistance - Unbiased autoclave	EN 60749-33	-

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IEC 60749-30

Edition 2.0 2020-08

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Semiconductor devices – Mechanical and climatic test methods –  
Part 30: Preconditioning of non-hermetic surface mount devices prior to  
reliability testing**

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques et climatiques –  
Partie 30: Préconditionnement des composants pour montage en surface non  
hermétiques avant les essais de fiabilité**

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## CONTENTS

FOREWORD .....	3
1 Scope .....	5
2 Normative references .....	5
3 Terms and definitions .....	6
4 General description .....	6
5 Test apparatus and materials .....	6
5.1 General.....	6
5.2 Moisture chamber .....	7
5.3 Solder equipment.....	7
5.4 Optical microscope .....	7
5.5 Electrical test equipment.....	7
5.6 Drying (bake) oven.....	7
5.7 Temperature cycle chamber (optional) .....	7
6 Procedure.....	7
6.1 General.....	7
6.2 Initial measurements.....	8
6.2.1 Electrical test.....	8
6.2.2 Visual inspection .....	8
6.3 Temperature cycling (optional) .....	8
6.4 Drying (bake out) .....	8
6.5 Soak conditions for dry-packed SMDs.....	8
6.5.1 General.....	8
6.5.2 Method A for dry-packed SMDs in accordance with IEC 60749-20 .....	8
6.5.3 Method B for dry-packed SMDs in accordance with IEC 60749-20 .....	8
6.6 Soak conditions for non-dry-packed SMDs in accordance with IEC 60749-20.....	8
6.7 Solder reflow.....	9
6.7.1 Solder reflow procedure.....	9
6.7.2 Solder attachment after reflow .....	9
6.8 Flux application simulation (optional) .....	10
6.8.1 Flux application .....	10
6.8.2 Cleaning and drying after flux application .....	10
6.9 Final measurements.....	10
6.9.1 Electrical test.....	10
6.9.2 Visual inspection .....	10
6.10 Applicable reliability tests.....	10
7 Summary .....	10
Table 1 – Preconditioning sequence flow – Method A (condition A2) in accordance with IEC 60749-20 (dry-packed devices) .....	11
Table 2 – Preconditioning sequence flow – Method B (conditions B2 to B6) in accordance with IEC 60749-20 (dry-packed devices) .....	11
Table 3 – Preconditioning sequence flow – Conditions A1 and B1 in accordance with IEC 60749-20 (non dry-packed devices) .....	12



## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –****Part 30: Preconditioning of non-hermetic surface  
mount devices prior to reliability testing**

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International Standard IEC 60749-30 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2005 and Amendment 1:2011. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) inclusion of new Clause 3;
- b) expansion of 6.7 on solder reflow;
- c) inclusion of explanatory notes and clarifications.